MOTOROLA
SEMICONDUCTORS
P.O. BOX 20912 • PHOENIX, ARIZONA 85036

TL061
TL062
TL064

LOW POWER JFET INPUT OPERATIONAL AMPLIFIER

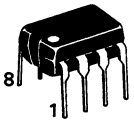
These JFET input operational amplifiers are designed for low power applications. They feature high input impedance, low input bias current and low input offset current. Advanced design techniques allow for higher slew rates, gain bandwidth products and output swing. The TL061 device provides for the external null adjustment of input offset voltage.

These devices are specified over the commercial, vehicular and military temperature ranges. The commercial and vehicular devices are available in Plastic dual in-line and SOIC packages. The military devices are available in Ceramic dual in-line packages.

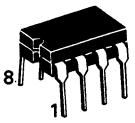
- Low Supply Current — 200 μA/Amplifier
- Low Input Bias Current — 5.0 pA
- High Gain Bandwidth — 2.0 MHz
- High Slew Rate — 6.0 V/μs
- High Input Impedance — 10^{12} Ω
- Large Output Voltage Swing — ±14 V
- Output Short Circuit Protection

LOW POWER JFET INPUT OPERATIONAL AMPLIFIERS

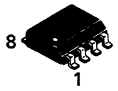
SILICON MONOLITHIC INTEGRATED CIRCUITS



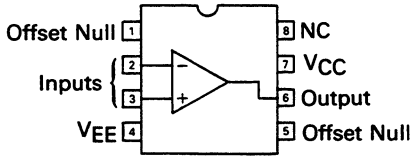
P SUFFIX
PLASTIC PACKAGE
CASE 626-04



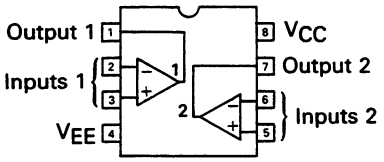
JG SUFFIX
CERAMIC PACKAGE
CASE 693-02



D SUFFIX
PLASTIC PACKAGE
CASE 751-02
SO-8



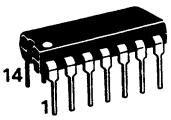
(Single, Top View)



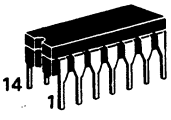
(Dual, Top View)

ORDERING INFORMATION

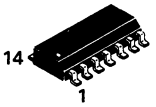
Op Amp Function	Device	Tested Temperature Range	Package
Single	TL061CD, ACD, BCD	0 to +70°C	SO-8
	TL061CP, ACP, BCP	0 to +70°C	Plastic DIP
	TL061VD	−40 to +85°C	SO-8
	TL061VP	−40 to +85°C	Plastic DIP
	TL061MJG	−55 to +125°C	Ceramic DIP
Dual	TL062CD, ACD, BCD	0 to +70°C	SO-8
	TL062CP, ACP, BCP	0 to +70°C	Plastic DIP
	TL062VD	−40 to +85°C	SO-8
	TL062VP	−40 to +85°C	Plastic DIP
	TL062MJG	−55 to +125°C	Ceramic DIP
Quad	TL064CD, ACD, BCD	0 to +70°C	SO-14
	TL064CN, ACN, BCN	0 to +70°C	Plastic DIP
	TL064VD	−40 to +85°C	SO-14
	TL064VP	−40 to +85°C	Plastic DIP
	TL064MJ	−55 to +125°C	Ceramic DIP



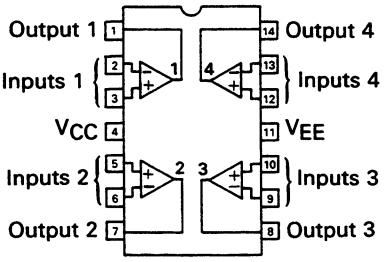
N SUFFIX
PLASTIC PACKAGE
CASE 646-06



J SUFFIX
CERAMIC PACKAGE
CASE 632-02



D SUFFIX
PLASTIC PACKAGE
CASE 751A-02
SO-14



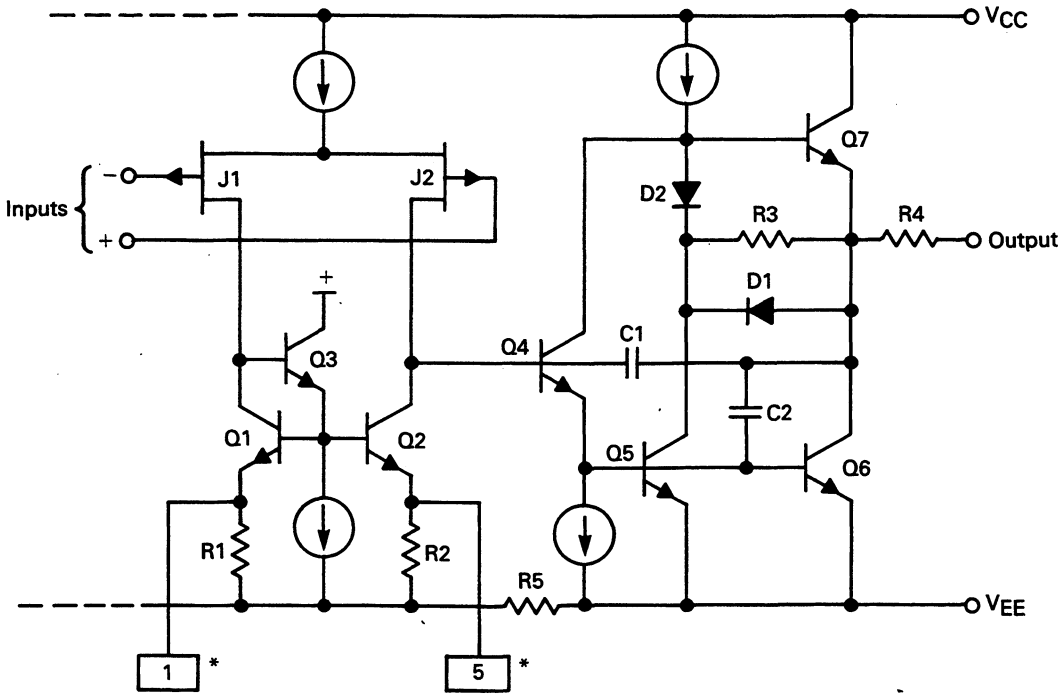
(Quad, Top View)

MAXIMUM RATINGS

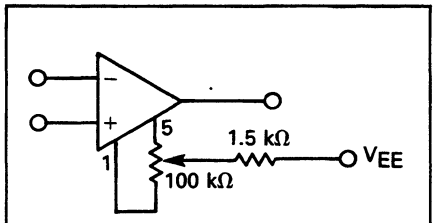
Rating	Symbol	Value	Unit
Supply Voltage (from V_{CC} to V_{EE})	V_S	+36	V
Input Differential Voltage Range (Note 1)	V_{IDR}	±30	V
Input Voltage Range (Notes 1 and 2)	V_{IR}	±15	V
Output Short-Circuit Duration (Note 3)	t_S	Indefinite	Seconds
Operating Junction Temperature (Note 3) Ceramic Package Plastic Package	T_J	 +160 +150	°C
Storage Temperature Range Ceramic Package Plastic Package	T_{stg}	 −65 to +160 −60 to +150	°C

NOTES:
1. Differential voltages are at the noninverting input terminal with respect to the inverting input terminal.
2. The magnitude of the input voltage must never exceed the magnitude of the supply or 15 volts, whichever is less.
3. Power dissipation must be considered to ensure maximum junction temperature (T_J) is not exceeded. (See Figure 1.)

EQUIVALENT CIRCUIT SCHEMATIC (EACH AMPLIFIER)



*Null adjustment pins for TL061 only.



TL061 input offset voltage null adjust circuit

DC ELECTRICAL CHARACTERISTICS (V_{CC} = +15 V, V_{EE} = −15 V, T_A = 0°C to +70°C, unless otherwise noted)

Characteristic	Symbol	TL061BC TL062BC TL064BC			TL061AC TL062AC TL064AC			TL061C TL062C TL064C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
Input Offset Voltage (R_S = 50 Ω, V_O = 0 V)	V_{IO}										mV
T_A = 25°C		—	2.0	3.0	—	3.0	6.0	—	3.0	15	
T_A = 0°C to +70°C		—	—	5.0	—	—	7.5	—	—	20	
Average Temperature Coefficient for Offset Voltage (R_S = 50 Ω, V_O = 0 V)	$\Delta V_{IO}/\Delta T$	—	10	—	—	10	—	—	10	—	μV/°C
Input Offset Current (V_{CM} = 0 V, V_O = 0 V)	I_{IO}										
T_A = 25°C		—	0.5	100	—	0.5	100	—	0.5	200	pA
T_A = 0°C to +70°C		—	—	2.0	—	—	2.0	—	—	2.0	nA
Input Bias Current (V_{CM} = 0 V, V_O = 0 V)	I_{IB}										
T_A = 25°C		—	3.0	200	—	3.0	200	—	3.0	200	pA
T_A = 0°C to +70°C		—	—	7.0	—	—	7.0	—	—	10	nA
Input Common Mode Voltage Range (T_A = 25°C)	V_{ICR}	—	+14.5	+11.5	—	+14.5	+11.5	—	+14.5	+11	V
		−11.5	−12	—	−11.5	−12	—	−11	−12	—	
Large Signal Voltage Gain (R_L = 10 kΩ, V_O = ±10 V)	A_{VOL}										V/mV
T_A = 25°C		4.0	58	—	4.0	58	—	3.0	58	—	
T_A = 0°C to +70°C		4.0	—	—	4.0	—	—	3.0	—	—	
Output Voltage Swing (R_L = 10 kΩ, V_{ID} = 1.0 V)											V
T_A = 25°C	V_O+	+10	+14	—	+10	+14	—	+10	+14	—	
	V_O-	—	−14	−10	—	−14	−10	—	−14	−10	
T_A = 0°C to +70°C	V_O+	+10	—	—	+10	—	—	+10	—	—	
	V_O-	—	—	−10	—	—	−10	—	—	−10	
Common Mode Rejection (R_S = 50 Ω, V_{CM} = V_{ICR} min, V_O = 0 V, T_A = 25°C)	CMR	80	84	—	80	84	—	70	84	—	dB
Power Supply Rejection (R_S = 50 Ω, V_{CM} = 0 V, V_O = 0, T_A = 25°C)	PSR	80	86	—	80	86	—	70	86	—	dB
Power Supply Current (each amplifier) (No Load, V_O = 0 V, T_A = 25°C)	I_D	—	200	250	—	200	250	—	200	250	μA
Total Power Dissipation (each amplifier) (No Load, V_O = 0 V, T_A = 25°C)	P_D	—	6.0	7.5	—	6.0	7.5	—	6.0	7.5	mW

DC ELECTRICAL CHARACTERISTICS (V_{CC} = +15 V, V_{EE} = −15 V, T_A = T_{low} to T_{high} (Note 4), unless otherwise noted)

Characteristic	Symbol	TL061M,V TL062M,V Min	TL061M,V TL062M,V Typ	TL061M,V TL062M,V Max	TL064M,V Min	TL064M,V Typ	TL064M,V Max	Unit
Input Offset Voltage (R_S = 50 Ω, V_O = 0 V)	V_{IO}							mV
T_A = 25°C		—	3.0	6.0	—	3.0	9.0	
T_A = T_{low} to T_{high}		—	—	9.0	—	—	15	
Average Temperature Coefficient of Offset Voltage (R_S = 50 Ω, V_O = 0 V)	$\Delta V_{IO}/\Delta T$	—	10	—	—	10	—	μV/°C
Input Offset Current (V_{CM} = 0 V, V_O = 0 V)	I_{IO}							
T_A = 25°C		—	5.0	100	—	5.0	100	pA
T_A = T_{low} to T_{high}		—	—	20	—	—	20	nA
Input Bias Current (V_{CM} = 0 V, V_O = 0 V)	I_{IB}							
T_A = 25°C		—	30	200	—	30	200	pA
T_A = T_{low} to T_{high}		—	—	50	—	—	50	nA
Input Common Mode Voltage Range (T_A = 25°C)	V_{ICR}	—	+14.5	+11.5	—	+14.5	+11.5	V
		−11.5	−12	—	−11.5	−12	—	
Large Signal Voltage Gain (R_L = 10 kΩ, V_O = ±10 V)	A_{VOL}							V/mV
T_A = 25°C		4.0	58	—	4.0	58	—	
T_A = T_{low} to T_{high}		4.0	—	—	4.0	—	—	
Output Voltage Swing (R_L = 10 kΩ, V_{ID} = 1.0 V)								V
T_A = 25°C	V_O+	+10	+14	—	+10	+14	—	
	V_O−	—	−14	−10	—	−14	−10	
T_A = T_{low} to T_{high}	V_O+	+10	—	—	+10	—	—	
	V_O−	—	—	−10	—	—	−10	
Common Mode Rejection (R_S = 50 Ω, V_{CM} = V_{ICR} min, V_O = 0 V, T_A = 25°C)	CMR	80	84	—	80	84	—	dB
Power Supply Rejection (R_S = 50 Ω, V_{CM} = 0 V, V_O = 0 V, T_A = 25°C)	PSR	80	86	—	80	86	—	dB
Power Supply Current (each Amplifier) (No Load, V_O = 0 V, T_A = 25°C)	I_D	—	200	250	—	200	250	μA
Total Power Dissipation (each Amplifier) (No Load, V_O = 0 V, T_A = 25°C)	P_D	—	6.0	7.5	—	6.0	7.5	mW

Note 4. TL06XM T_{low} = −55°C T_{high} = +125°C
TL06XV T_{low} = −40°C T_{high} = +85°C

AC ELECTRICAL CHARACTERISTICS (V_{CC} = +15 V, V_{EE} = −15 V, T_A = +25°C, unless otherwise noted)

Characteristic		Symbol	Min	Typ	Max	Unit
Slew Rate (V_{in} = −10 V to +10 V, R_L = 10 kΩ, C_L = 100 pF, A_V = +1.0)		SR	2.0	6.0	—	V/μs
Rise Time (V_{in} = 20 mV, R_L = 10 kΩ, C_L = 100 pF, A_V = +1.0)		t_r	—	0.1	—	μs
Overshoot (V_{in} = 20 mV, R_L = 10 kΩ, C_L = 100 pF, A_V = +1.0)		OS	—	10	—	%
Settling Time		t_S				μs
(V_{CC} = +15 V, V_{EE} = −15 V, A_V = −1.0,	To within 10 mV		—	1.6	—	
R_L = 10 kΩ, V_O = 0 V to +10 V step)	To within 1.0 mV		—	2.2	—	
Gain Bandwidth Product (f = 200 kHz)		GBW	—	2.0	—	MHz
Equivalent Input Noise (R_S = 100 Ω, f = 1.0 kHz)		e_n	—	47	—	nV/√Hz
Input Resistance		R_i	—	10^{12}	—	Ω
Channel Separation (f = 10 kHz)		CS	—	120	—	dB

TYPICAL PERFORMANCE CURVES

FIGURE 1 — MAXIMUM POWER DISSIPATION versus TEMPERATURE FOR PACKAGE VARIATIONS

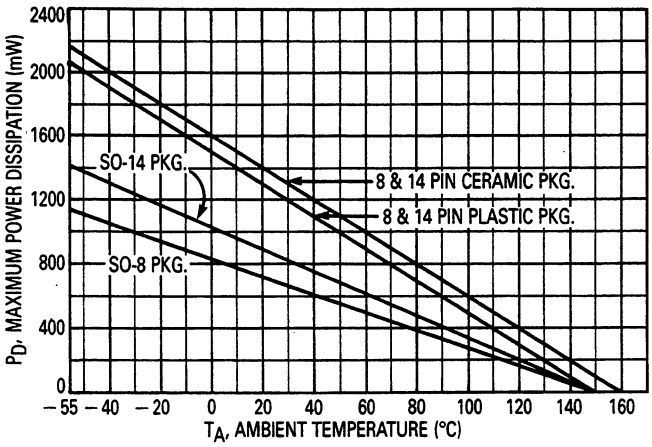


FIGURE 2 — OUTPUT VOLTAGE SWING versus SUPPLY VOLTAGE

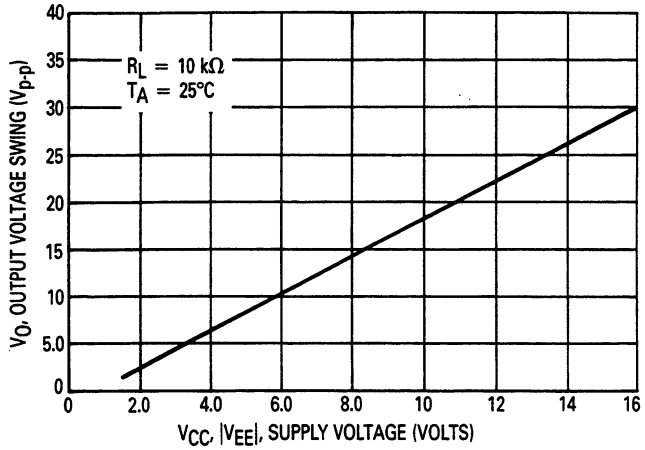


FIGURE 3 — OUTPUT VOLTAGE SWING versus TEMPERATURE

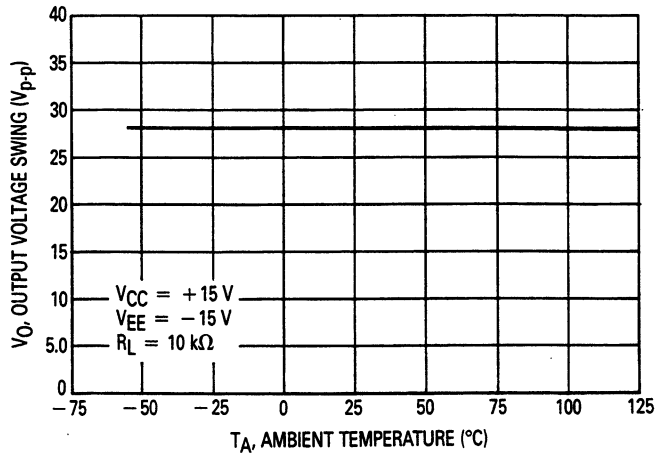


FIGURE 4 — OUTPUT VOLTAGE SWING versus LOAD RESISTANCE

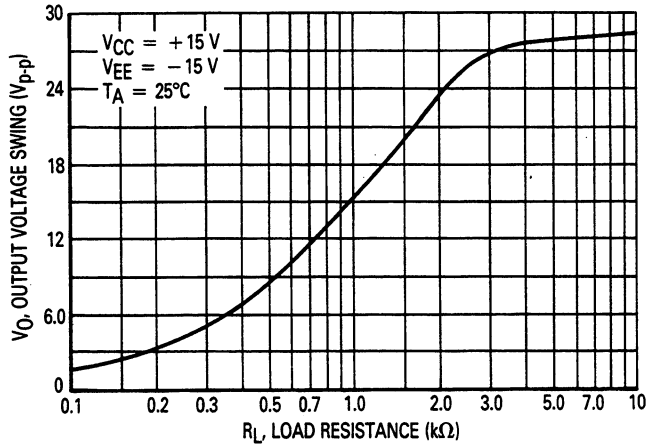


FIGURE 5 — OUTPUT VOLTAGE SWING versus FREQUENCY

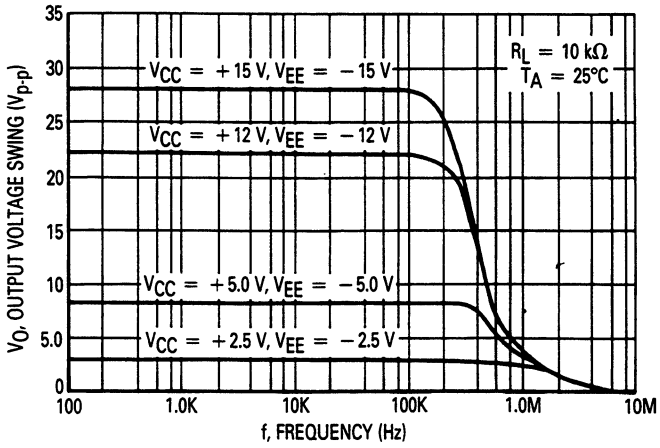


FIGURE 6 — LARGE SIGNAL VOLTAGE GAIN versus TEMPERATURE

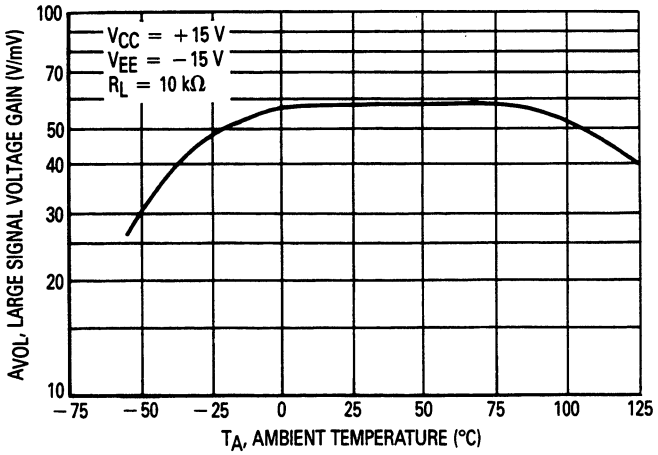


FIGURE 7 — OPEN-LOOP VOLTAGE GAIN AND PHASE versus FREQUENCY

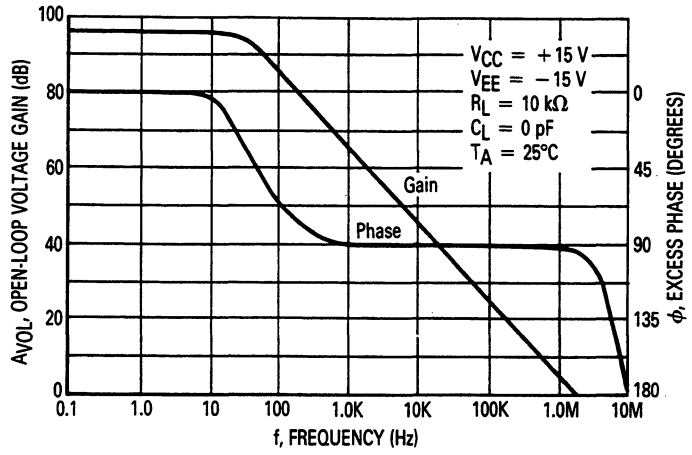


FIGURE 8 — SUPPLY CURRENT PER AMPLIFIER versus SUPPLY VOLTAGE

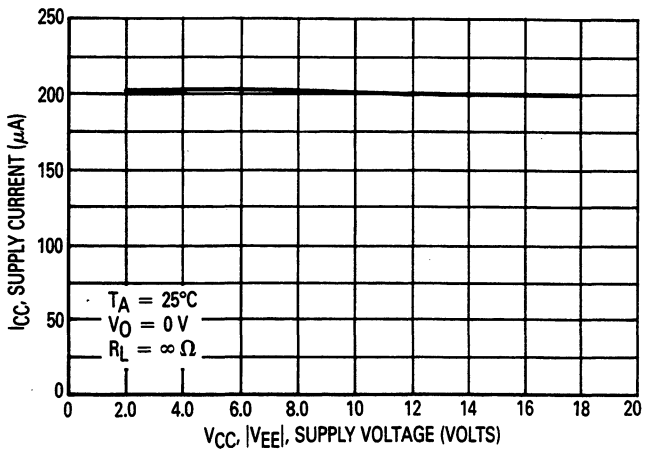


FIGURE 9 — SUPPLY CURRENT PER AMPLIFIER versus TEMPERATURE

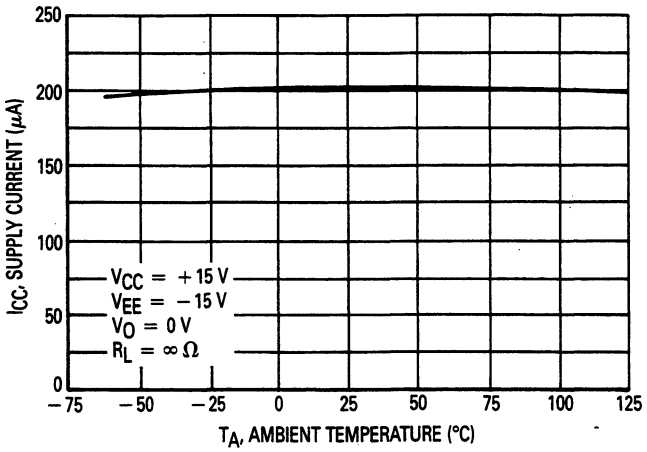


FIGURE 10 — TOTAL POWER DISSIPATION versus TEMPERATURE

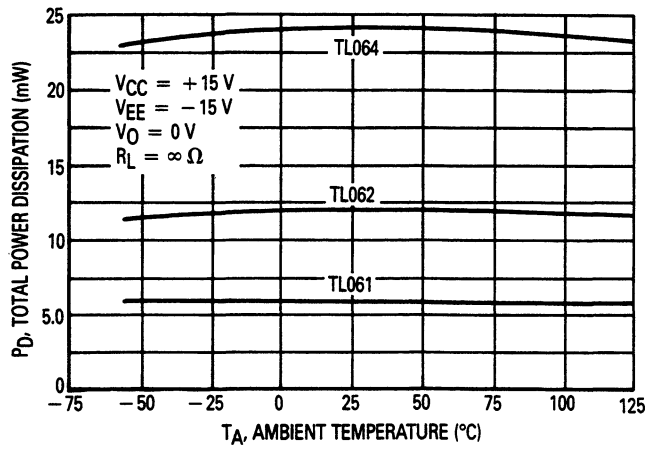


FIGURE 11 — COMMON-MODE REJECTION versus TEMPERATURE

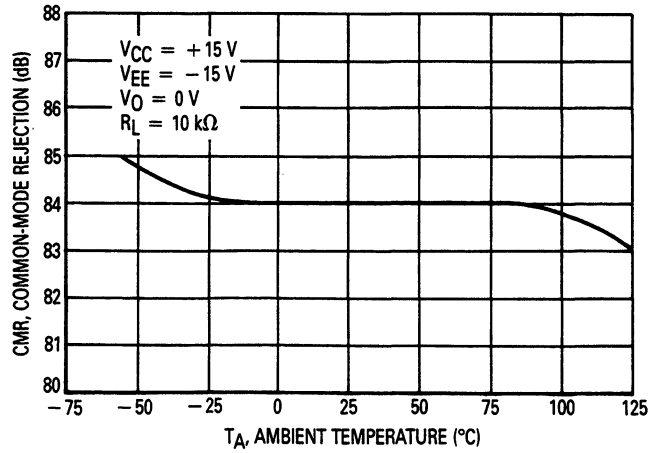


FIGURE 12 — COMMON-MODE REJECTION versus FREQUENCY

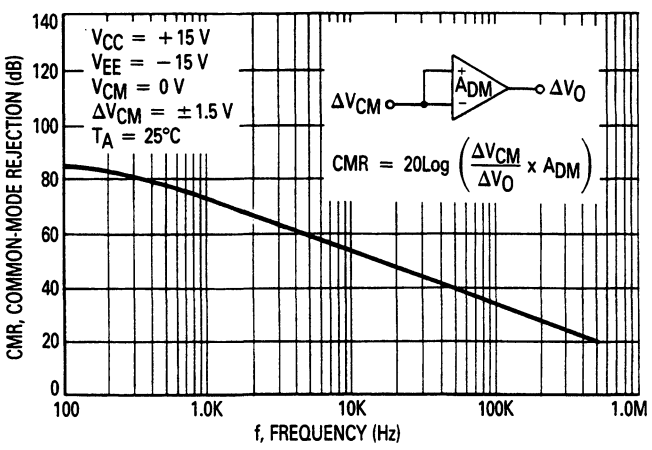


FIGURE 13 — POWER SUPPLY REJECTION versus FREQUENCY

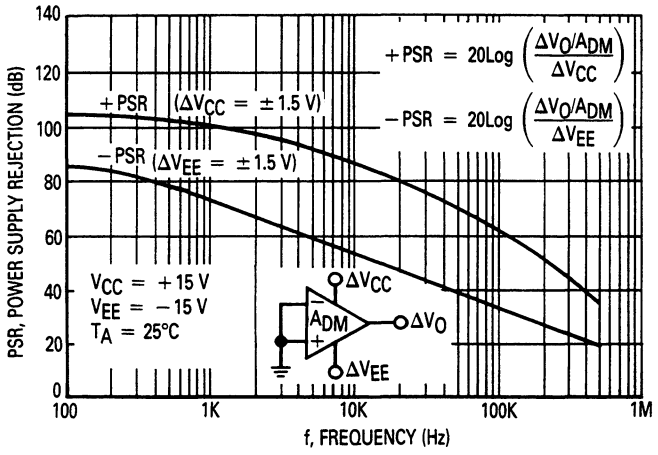


FIGURE 14 — NORMALIZED GAIN BANDWIDTH PRODUCT, SLEW RATE AND PHASE MARGIN versus TEMPERATURE

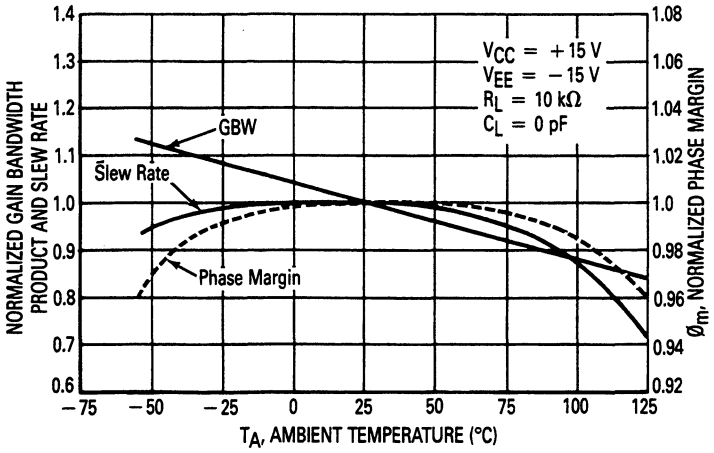


FIGURE 15 — INPUT BIAS CURRENT versus TEMPERATURE

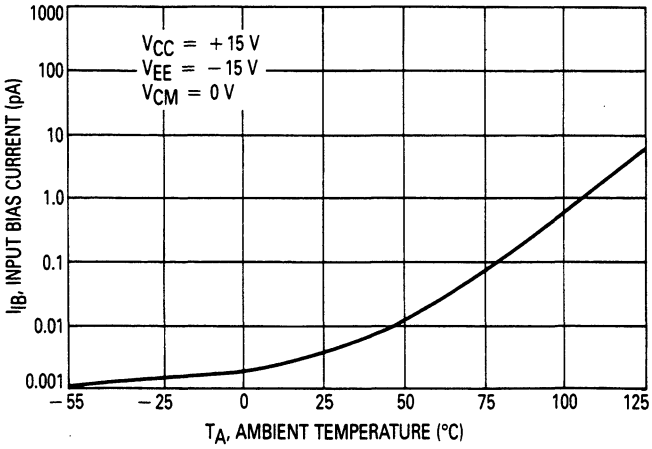


FIGURE 16 — INPUT NOISE VOLTAGE versus FREQUENCY

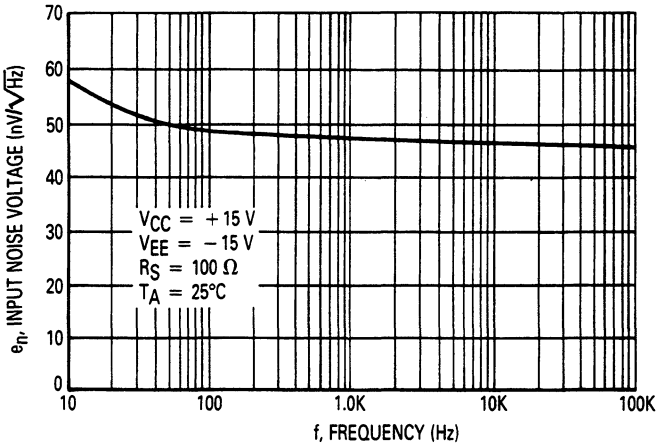


FIGURE 17 — SMALL SIGNAL RESPONSE

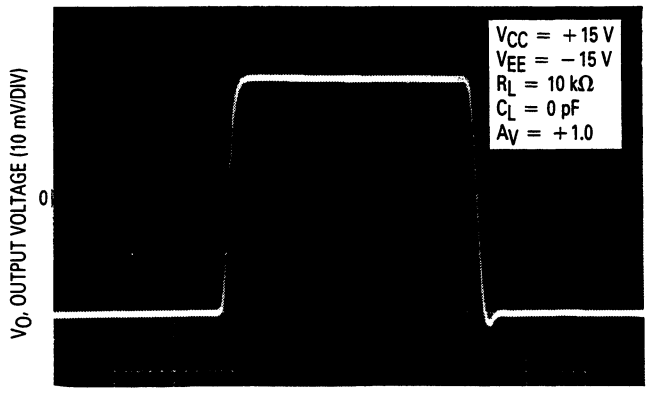


FIGURE 18 — LARGE SIGNAL RESPONSE

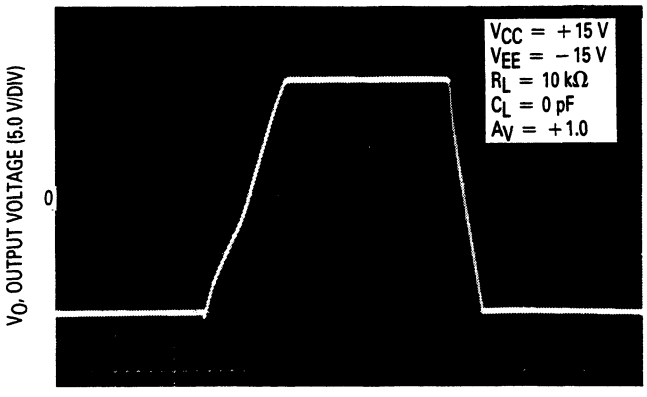


FIGURE 19 — AC AMPLIFIER

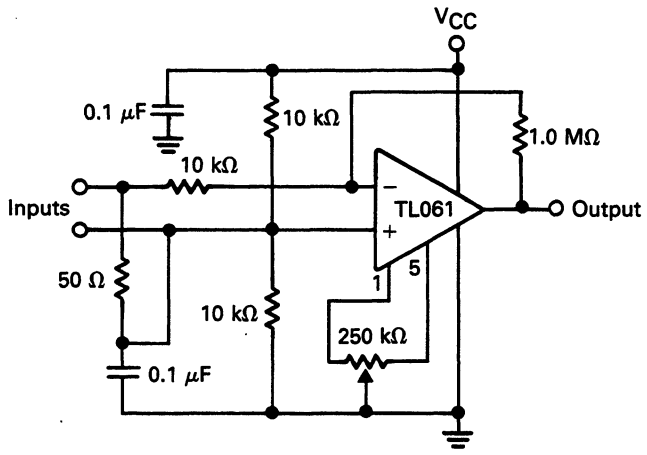


FIGURE 20 — HIGH-Q NOTCH FILTER

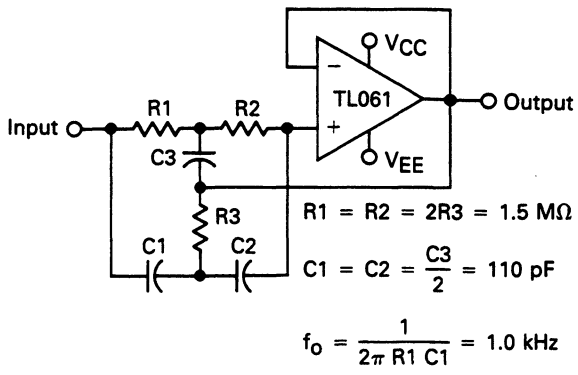


FIGURE 21 — INSTRUMENTATION AMPLIFIER

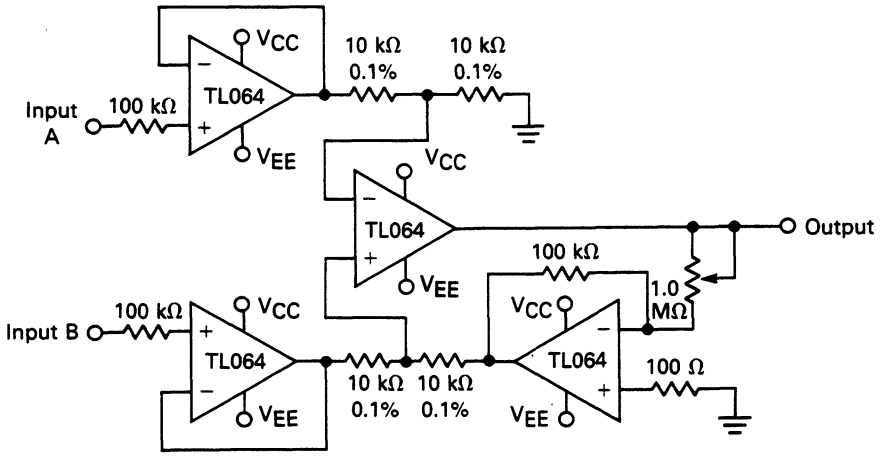
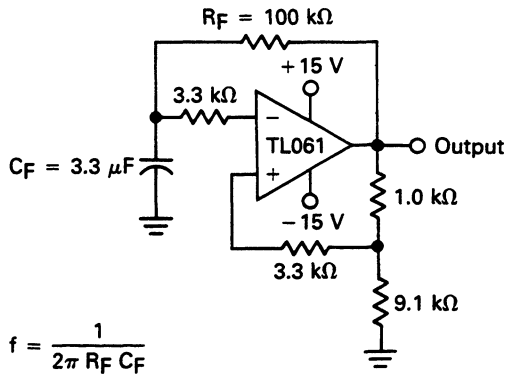
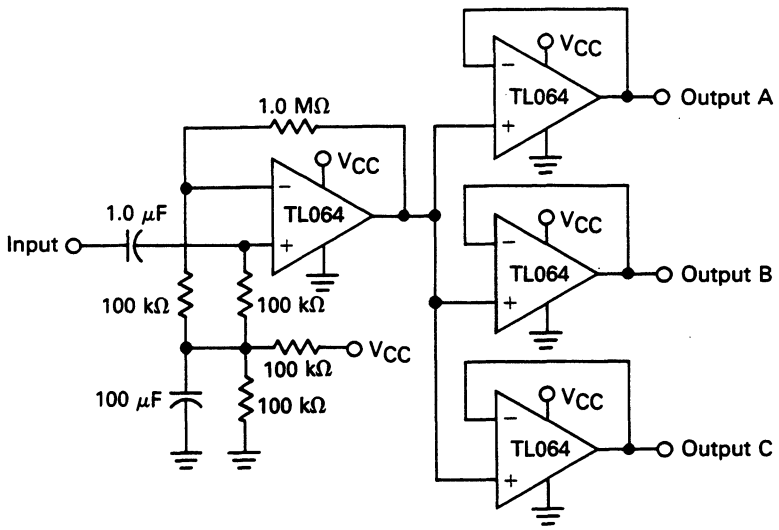


FIGURE 22 — 0.5 Hz SQUARE-WAVE OSCILLATOR

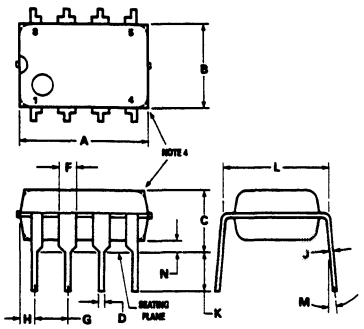


$$f = \frac{1}{2\pi R_F C_F}$$

FIGURE 23 — AUDIO DISTRIBUTION AMPLIFIER



OUTLINE DIMENSIONS

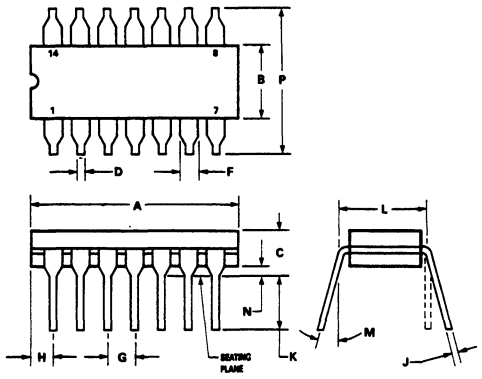


NOTES:
1. LEAD POSITIONAL TOLERANCE:
   ⌖ ⌀ 0.13 (0.005) Ⓜ | T | A Ⓜ | B Ⓜ
2. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
3. PACKAGE CONTOUR OPTIONAL (ROUND OR SQUARE CORNERS).
4. DIMENSIONS A AND B ARE DATUMS.
5. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

STYLE 1:
PIN 1. AC IN
2. DC + IN
3. DC − IN
4. AC IN
5. GROUND
6. OUTPUT
7. AUXILIARY
8. V_{CC}

DIM	MILLIMETERS MIN	MILLIMETERS MAX	INCHES MIN	INCHES MAX
A	9.40	10.16	0.370	0.400
B	6.10	6.60	0.240	0.260
C	3.94	4.45	0.155	0.175
D	0.38	0.51	0.015	0.020
F	1.02	1.52	0.040	0.060
G	2.54 BSC		0.100 BSC	
H	0.76	1.27	0.030	0.050
J	0.20	0.30	0.008	0.012
K	2.92	3.43	0.115	0.135
L	7.62 BSC		0.300 BSC	
M	—	10°	—	10°
N	0.51	0.76	0.020	0.030

P SUFFIX
PLASTIC PACKAGE
CASE 626-04

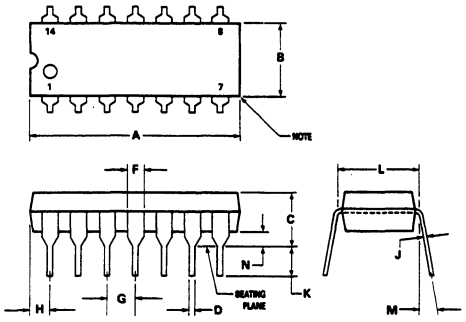


DIM	MILLIMETERS MIN	MILLIMETERS MAX	INCHES MIN	INCHES MAX
A	16.8	19.9	0.660	0.785
B	5.59	7.11	0.220	0.280
C	—	5.08	—	0.200
D	0.381	0.584	0.015	0.023
F	0.77	1.77	0.030	0.070
G	2.54 BSC		0.100 BSC	
J	0.203	0.381	0.008	0.015
K	2.54	—	0.100	—
L	7.62 BSC		0.300 BSC	
M	—	15°	—	15°
N	0.51	0.76	0.020	0.030
P	—	8.25	—	0.325

NOTES:
1. ALL RULES AND NOTES ASSOCIATED WITH MO-001 AA OUTLINE SHALL APPLY.
2. DIMENSION "L" TO CENTER OF LEADS WHEN FORMED PARALLEL.
3. LEADS WITHIN 0.25 mm (0.010) DIA OF TRUE POSITION AT SEATING PLANE AND MAXIMUM MATERIAL CONDITION.

All JEDEC dimensions and notes apply.

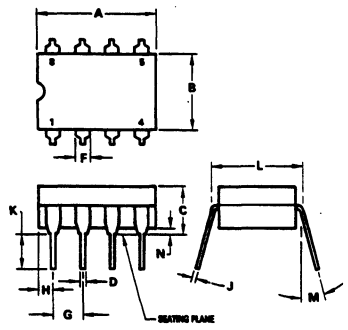
J SUFFIX
CERAMIC PACKAGE
CASE 632-02



NOTES:
1. LEADS WITHIN 0.13 mm (0.005) RADIUS OF TRUE POSITION AT SEATING PLANE AT MAXIMUM MATERIAL CONDITION.
2. DIMENSION "L" TO CENTER OF LEADS WHEN FORMED PARALLEL.
3. DIMENSION "B" DOES NOT INCLUDE MOLD FLASH.
4. ROUNDED CORNERS OPTIONAL

DIM	MILLIMETERS MIN	MILLIMETERS MAX	INCHES MIN	INCHES MAX
A	18.16	19.56	0.715	0.770
B	6.10	6.60	0.240	0.260
C	3.69	4.69	0.145	0.185
D	0.38	0.53	0.015	0.021
F	1.02	1.78	0.040	0.070
G	2.54 BSC		0.100 BSC	
H	1.32	2.41	0.052	0.095
J	0.20	0.38	0.008	0.015
K	2.92	3.43	0.115	0.135
L	7.62 BSC		0.300 BSC	
M	0°	10°	0°	10°
N	0.39	1.01	0.015	0.039

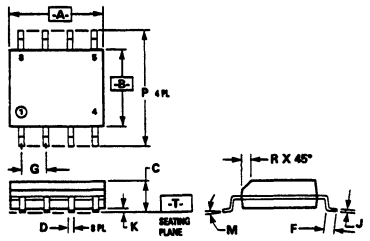
N SUFFIX
PLASTIC PACKAGE
CASE 646-06



NOTES:
1. LEADS WITHIN 0.13 mm (0.005) RAD OF TRUE POSITION AT SEATING PLANE AT MAXIMUM MATERIAL CONDITION.
2. DIMENSION "L" TO CENTER OF LEADS WHEN FORMED PARALLEL.

DIM	MILLIMETERS MIN	MILLIMETERS MAX	INCHES MIN	INCHES MAX
A	9.91	10.92	0.390	0.430
B	6.22	6.99	0.245	0.275
C	4.32	5.08	0.170	0.200
D	0.41	0.51	0.016	0.020
F	1.40	1.65	0.055	0.065
G	2.54 BSC		0.100 BSC	
H	1.14	1.65	0.045	0.065
J	0.20	0.30	0.008	0.012
K	3.18	4.06	0.125	0.160
L	7.37	7.87	0.290	0.310
M	—	15°	—	15°
N	0.51	1.02	0.020	0.040

JG SUFFIX
CERAMIC PACKAGE
CASE 693-02

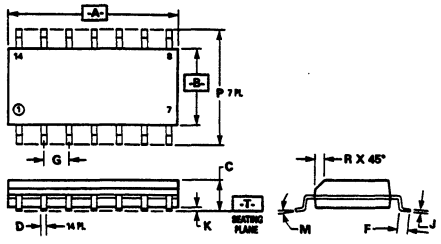


NOTES:
1. DIMENSIONS A AND B ARE DATUMS AND T IS A DATUM SURFACE.
2. POSITIONAL TOLERANCE FOR D DIMENSION (8 PLACES):
   ⌖ 0.25 (0.010) Ⓜ | T | B Ⓢ | A Ⓢ
3. POSITIONAL TOLERANCE FOR P DIMENSION (4 PLACES):
   ⌖ 0.25 (0.010) Ⓢ | B Ⓢ
4. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
5. CONTROLLING DIMENSION: MILLIMETER.
6. DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION.
7. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.

DIM	MILLIMETERS MIN	MILLIMETERS MAX	INCHES MIN	INCHES MAX
A	4.80	5.00	0.189	0.196
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27 BSC		0.050 BSC	
J	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
M	0°	7°	0°	7°
P	5.80	6.20	0.229	0.244
R	0.25	0.50	0.010	0.019

STYLE 1:
PIN 1. EMITTER
2. COLLECTOR
3. COLLECTOR
4. EMITTER
5. EMITTER
6. BASE
7. BASE
8. EMITTER

D SUFFIX
PLASTIC PACKAGE
CASE 751-02
SO-8



NOTES:
1. DIMENSIONS A AND B ARE DATUMS AND T IS A DATUM SURFACE.
2. POSITIONAL TOLERANCE FOR D DIMENSION (14 PLACES):
   ⌖ 0.25 (0.010) Ⓜ | T | B Ⓢ | A Ⓢ
3. POSITIONAL TOLERANCE FOR P DIMENSION (7 PLACES):
   ⌖ 0.25 (0.010) Ⓜ | B Ⓜ
4. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
5. CONTROLLING DIMENSION: MILLIMETER.
6. DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION.
7. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.

DIM	MILLIMETERS MIN	MILLIMETERS MAX	INCHES MIN	INCHES MAX
A	8.55	8.75	0.337	0.344
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27 BSC		0.050 BSC	
J	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
M	0°	7°	0°	7°
P	5.80	6.20	0.229	0.244
R	0.25	0.50	0.010	0.019

D SUFFIX
PLASTIC PACKAGE
CASE 751A-02
SO-14

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